

10/840,049

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	(copper adj surfaces) and contamination and oxidation and wafer and alkaline and solution and atmosphere and feature and process	USPAT	OR	ON	2005/05/10 17:20
L2	6	(copper adj surfaces) and contamination and oxidation and wafer and alkaline and solution and atmosphere and process	USPAT	OR	ON	2005/05/10 17:20
L3	6	2 and (expose or exposure or surface or newly or new or alkaline or solution or substantial or semiconductor or contamination or copper or feature or queue or subsequent or CMP or polishing or chemical or mechanical or pH or ammonia or sodium or hydroxide or dipping or spraying or spray or exposing or period or time or oxidation or sealed or inert or gas or purge or container)	USPAT	OR	ON	2005/05/10 18:08
L4	1	("6632288").PN.	USPAT	OR	OFF	2005/05/10 18:07
L5	1	("6065424").PN.	USPAT	OR	OFF	2005/05/10 18:08
L6	1	("6217667").PN.	USPAT	OR	OFF	2005/05/10 18:08
L7	1	4 and (expose or exposure or surface or newly or new or alkaline or solution or substantial or semiconductor or contamination or copper or feature or queue or subsequent or CMP or polishing or chemical or mechanical or pH or ammonia or sodium or hydroxide or dipping or spraying or spray or exposing or period or time or oxidation or sealed or inert or gas or purge or container)	USPAT	OR	ON	2005/05/10 18:08
L8	1	5 and (expose or exposure or surface or newly or new or alkaline or solution or substantial or semiconductor or contamination or copper or feature or queue or subsequent or CMP or polishing or chemical or mechanical or pH or ammonia or sodium or hydroxide or dipping or spraying or spray or exposing or period or time or oxidation or sealed or inert or gas or purge or container)	USPAT	OR	ON	2005/05/10 18:09
L9	1	6	USPAT	OR	ON	2005/05/10 18:08

L10	1	6 and (expose or exposure or surface or newly or new or alkaline or solution or substantial or semiconductor or contamination or copper or feature or queue or subsequent or CMP or polishing or chemical or mechanical or pH or ammonia or sodium or hydroxide or dipping or spraying or spray or exposing or period or time or oxidation or sealed or inert or gas or purge or container)	USPAT	OR	ON	2005/05/10 18:09
L11	1866	438/687	USPAT	OR	ON	2005/05/10 18:09
L12	3424	438/692	USPAT	OR	ON	2005/05/10 18:09
L13	1146	438/680	USPAT	OR	ON	2005/05/10 18:09
L14	572	438/681	USPAT	OR	ON	2005/05/10 18:09
L15	1482	438/700	USPAT	OR	ON	2005/05/10 18:09
L16	852	438/712	USPAT	OR	ON	2005/05/10 18:09
L17	760	438/770	USPAT	OR	ON	2005/05/10 18:10
L18	259	438/773	USPAT	OR	ON	2005/05/10 18:10
S18 3	0	(preventing adj Cu adj contamination) and oxidation	USPAT	OR	ON	2005/05/10 15:51
S18 4	0	(copper adj surfaces) and contamination and oxidation and wafer and alkaline and solution and atmosphere and queue and feature and process	USPAT	OR	ON	2005/05/10 17:10